DB3X314K

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Short reverse recovery time t_{rr}
- Small reverse current I_R
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

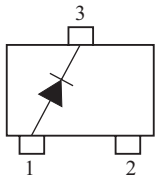
Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Package

- Code
  Mini3-G3-B
- Pin Name
  1: Anode
  2: N.C.
  3: Cathode

■ Marking Symbol: 4X

■ Internal Connection



■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Maximum peak reverse voltage	V_{RM}	30	V
Forward current	I_F	30	mA
Peak forward current	I_{FM}	150	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	–55 to +125	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

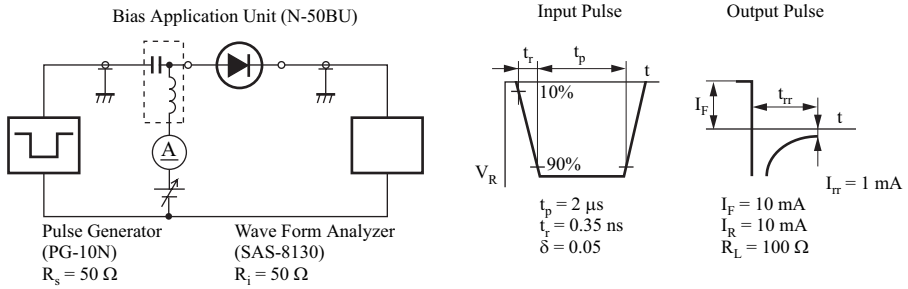
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 1$ mA			0.4	V
	V_{F2}	$I_F = 30$ mA			1.0	
Reverse current	I_R	$V_R = 30$ V			300	nA
Terminal capacitance	C_t	$V_R = 10$ V, f = 1 MHz		1.5		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 10$ mA, $I_{rr} = 1$ mA, $R_L = 100\ \Omega$		1.0		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

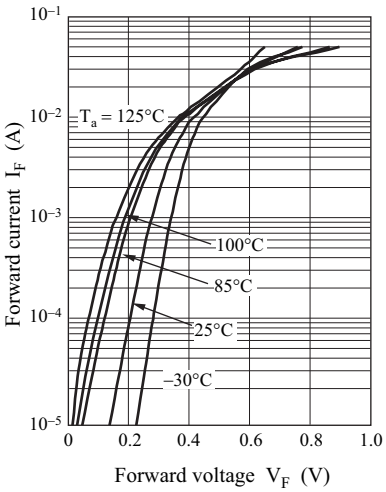
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 2 GHz

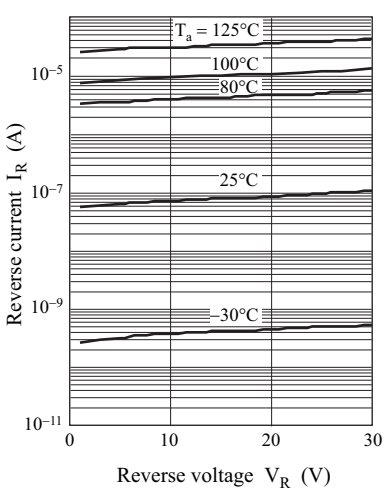
*: t_{rr} measurement circuit



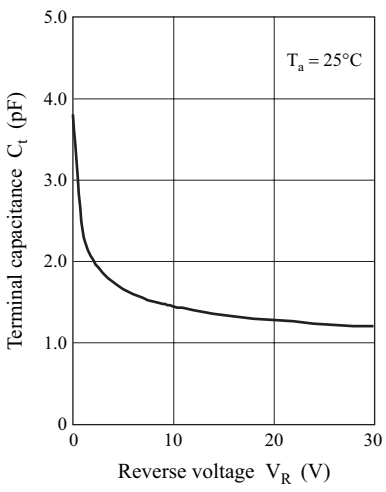
I_F — V_F



I_R — V_R

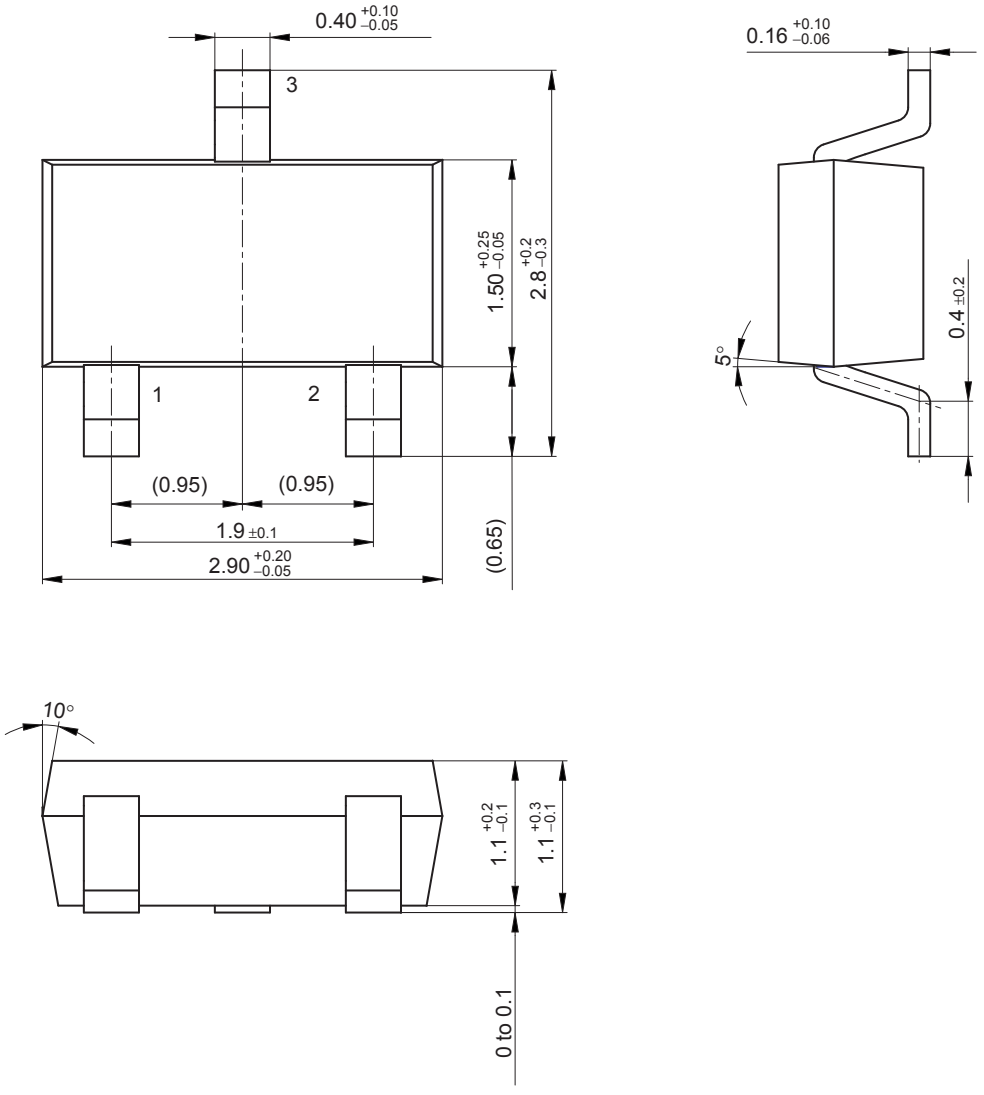


C_t — V_R



Mini3-G3-B

Unit: mm



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